E-NEWSLETTER
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MALAYSIA MADANI

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HIGHLIGHTS

From Capability to Competitiveness: Strengthening Malaysia's Semiconductor Supply Chain

INDUSTRY

The Unsung Heroes: Why Malaysia's Chip Success is Written in ESI

GOING GLOBAL SERIES

Heng Hiap Industries Sdn. Bhd. (HHI): Building Global Circularity Through Integrated Recycling

From the CEO's Desk

Steering Malaysia Towards an Outcome-Driven, High-Growth Future

Dear Valued Partners and Esteemed Stakeholders,

The global economy is being reshaped by rapid technological advancement, supply chain realignment and the accelerating adoption of artificial intelligence. In this environment, nations compete not only on cost and infrastructure, but also on the resilience of their industrial ecosystems. Malaysia is well positioned to seize these opportunities, drawing on its strong manufacturing base, deep industrial ecosystem, skilled workforce, diverse talent pool and strategic location at the heart of Southeast Asia.

This edition of MIDA's newsletter brings together insights and success stories that showcase the breadth of our industrial ambitions and the strong momentum behind them.

Our **Highlights** feature how Malaysia can move from capability to competitiveness in the semiconductor supply chain. Drawing on key discussions from SEMICON Southeast Asia 2026, it highlights why stronger supply chain integration, capability development and ecosystem collaboration are becoming increasingly important as AI, electric vehicles and advanced computing reshape global demand for next-generation chips. The article also highlights Malaysia's expanding role in advanced packaging, semiconductor equipment and ecosystem development, reinforcing the country's aspirations under the New Industrial Master Plan 2030 and the National Semiconductor Strategy.

Complementing this, our **Industry** segment shines a spotlight on the Engineering Supporting Industries — the precision machinists, automation specialists and tooling providers that form the backbone of Malaysia's semiconductor ecosystem. While often operating behind the scenes assumes a vital role in attracting quality investment. Strengthening this ecosystem will be essential as Malaysia continues to build its position as a trusted and competitive technology hub.

Our **Special Feature** on advanced packaging explores how Malaysia is positioning itself to meet the rapidly increasing demands of the AI era. Produced in collaboration with the Malaysia Printed Circuit Board and Advanced Packaging Association (MPMA), the feature charts Malaysia's trajectory in one of the semiconductor industry's fastest-growing segments — highlighting the strategic investments and partnerships shaping its next phase of growth.

In our **Going Global** segment, we feature Heng Hiap Industries Sdn. Bhd. — a Malaysian company that has transformed plastic waste into high-value recycled materials and now serves customers in 41 countries. HHI's journey demonstrates how Malaysian companies can build global success through innovation, sustainability and strong ecosystem partnerships. It is a powerful reminder that the circular economy is not only good for the environment but also creates meaningful commercial opportunities.

From the CEO's Desk

Collectively, the stories in this edition reflect how collaboration, innovation and capability development are strengthening Malaysia's industrial transformation. As we build a more resilient, high-value and future-ready economy, MIDA remains committed to facilitating quality investments, strengthening domestic industries and creating new opportunities for Malaysian companies to grow, innovate and compete globally.

I hope you enjoy this edition and find the stories, insights and perspectives both informative and inspiring. Together, they reflect the progress we are making and the exciting opportunities that lie ahead for Malaysia's industrial future.

DATUK SIKH SHAMSUL IBRAHIM SIKH ABDUL MAJID
Chief Executive Officer
Malaysian Investment Development Authority (MIDA)

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In this issue

From Capability to Competitiveness: Strengthening Malaysia's Semiconductor Supply Chain

As artificial intelligence (AI), advanced computing and next-generation mobility technologies reshape global industries, the semiconductor sector is entering a new phase of transformation. Increasingly, competitiveness is no longer determined by the strength of individual companies alone, but by the capabilities of entire ecosystems.

For Malaysia, this presents both a significant opportunity and an important challenge.

These themes took centre stage during the Strategic Panel Session, Advancing Malaysia's Semiconductor Ecosystem Through Strategic Supply Chain Integration & Capability Enhancement, held in conjunction with SEMICON SEA 2026. Moderated by YBhg. Dato' Dr. Mohd Sofi Osman, the session brought together leading voices across the semiconductor value chain, including:

- Mr. Amarjit Sandhu, Corporate Vice President of Assembly and Test NAND Operations at Micron Memory Malaysia;
- Mr. Noorazidi Che Azib, Vice President of Inari Technology Sdn Bhd;
- Mr. Henk-Jan Jonge Poerink, Senior Vice President Global Operations and Managing Director of Besi Apac Sdn Bhd;
- Mr. Shahrel Mohd Zain, Group Chief Operating Officer of Betamek Berhad; as well as
- Mr. ET Tan and Mr. Peter Charvat representing the Malaysia Advanced Packaging Consortium (MAPC).

Collectively, the panellists offered valuable perspectives on how Malaysia can strengthen its position within an increasingly complex and technology-driven semiconductor landscape.

AI Driving the Next Wave of Semiconductor Growth

The rise of AI is fundamentally reshaping global demand for semiconductors. From data centres and cloud computing to autonomous systems and advanced electronics, the need for higher-performance chips, greater computing power and larger memory capacity continues to accelerate.

Beyond technological advancement, global semiconductor supply chains are increasingly being shaped by resilience considerations. Recent disruptions, geopolitical tensions and efforts by major economies to diversify production have heightened the importance of trusted manufacturing locations and reliable supplier ecosystems. Malaysia's longstanding reputation as a stable and trusted semiconductor hub places the country in a favourable position to capture emerging investment and supply chain diversification opportunities.

According to **Micron Memory Malaysia** the country is already assuming an important role in supporting this global transformation. The company produces advanced memory and

storage solutions used in AI-related applications while maintaining strong linkages with local suppliers through procurement, ecosystem development and supply chain partnerships.

This reflects the broader multiplier effect of multinational investments in Malaysia. Beyond creating jobs and expanding production capacity, global companies contribute to technology transfer, supplier development and ecosystem strengthening, helping local businesses integrate into increasingly sophisticated value chains.

Moving Beyond Manufacturing Excellence

Malaysia has long established itself as a trusted semiconductor manufacturing hub, supported by decades of industry experience, a skilled workforce and a mature supply chain ecosystem. However, the next phase of growth will increasingly depend on the country's ability to move into higher-value activities.

Industry players highlighted the growing importance of automation, robotics, AI-enabled manufacturing and advanced process technologies in enhancing productivity and competitiveness. Rather than moving away from manufacturing, Malaysian companies must continue building upon their strengths while expanding into more sophisticated capabilities and value-added activities

According to **Inari Technology,** this evolution requires greater adoption of autonomous manufacturing systems, advanced packaging participation and deeper integration with local suppliers. Similarly, **Besi Apac** emphasised that Malaysia's strong talent pool, infrastructure, business-friendly environment and well-developed supply chain ecosystem continue to make the country an attractive destination for high-technology manufacturing and semiconductor equipment activities.

Beyond manufacturing and packaging, semiconductor equipment represents another area of strategic opportunity. Building stronger local capabilities in equipment engineering, precision manufacturing and supporting technologies can create additional layers of value creation while enhancing the resilience of Malaysia's broader semiconductor ecosystem.

These strengths have enabled Malaysia to remain a key node within global semiconductor supply chains. The challenge now is to build on this foundation and capture greater value across the ecosystem. As semiconductor technologies become increasingly complex, the greatest economic returns are accruing to companies and ecosystems involved in design, advanced manufacturing, packaging innovation, equipment development and intellectual property creation. Strengthening Malaysia's participation in these segments will be critical to increasing domestic value capture and long-term industry competitiveness.

Advanced Packaging: Malaysia's Next Frontier

Among the strongest themes emerging from the discussion was the growing importance of advanced packaging, widely regarded as one of the most critical growth areas in the semiconductor industry.

Traditionally, semiconductor packaging involved integrating a single chip into a package. Today, technologies such as AI, electric vehicles (EVs), alternative energy systems and high-performance computing require increasingly sophisticated packaging solutions capable of integrating multiple chiplets into a single high-performance system.

As a result, advanced packaging is rapidly becoming a strategic differentiator within the semiconductor value chain.

Representatives from **MAPC** noted that while Malaysia has long been recognised for its strengths in conventional semiconductor packaging and testing, future competitiveness will depend on the industry's ability to develop advanced packaging capabilities that support emerging technologies and next-generation applications.

Perhaps the most significant takeaway from the session was the recognition that competition is no longer company versus company, but supply chain versus supply chain. Success increasingly depends on how effectively ecosystems can collaborate, innovate and respond to evolving market demands.

Malaysia's established strengths in assembly, packaging and testing provide a natural foundation for advancing into higher-value packaging technologies. Unlike many emerging semiconductor segments that require entirely new ecosystems, advanced packaging allows Malaysia to leverage decades of accumulated expertise while progressively moving up the value chain.

Building a More Integrated Ecosystem

Meeting these challenges requires a coordinated effort across industry, academia and government.

As Malaysia advances its National Semiconductor Strategy (NSS), MIDA serves as a key facilitator in strengthening ecosystem linkages, attracting strategic investments, supporting supplier development and fostering collaboration across industry, academia and government. These efforts are helping to accelerate capability upgrading while positioning Malaysia to compete more effectively in higher value semiconductor segments.

The formation of MAPC represents one example of how industry players are working together to strengthen Malaysia's capabilities in advanced packaging. By bringing together companies with expertise spanning IC design, packaging, testing and equipment development, the consortium aims to accelerate capability building while fostering greater collaboration across the ecosystem.

The discussion also highlighted the importance of talent development and supplier readiness. As technologies become more complex and product cycles shorten, suppliers must meet increasingly demanding requirements in quality, consistency, resilience, speed and innovation.

Equally important is the need to accelerate technology adoption. Capabilities such as smart manufacturing, automation, AI-driven analytics and digital operations are rapidly becoming baseline requirements rather than competitive advantages.

For sectors such as automotive electronics, these trends present significant opportunities. **Betamek** highlighted the growing demand for EV controllers, telematics systems, safety technologies and smart mobility solutions, demonstrating how Malaysia's broader electronics ecosystem can support the future of transportation and connected mobility.

Positioning Malaysia for the Future

The priorities identified during the session closely align with the objectives of the country's NSS, which seeks to strengthen its position across higher-value segments of the semiconductor value chain, including IC design, advanced packaging, semiconductor equipment and research and development.

Malaysia enters this next phase from a position of strength. The country has built a globally recognised semiconductor ecosystem over more than five decades, supported by strong industrial capabilities, experienced talent and long-standing investor confidence.

Maintaining competitiveness will require greater speed, deeper collaboration and a stronger focus on capability development. The opportunity is no longer simply to participate in global semiconductor supply chains, but to play a larger role in shaping them.

As the global semiconductor landscape continues to evolve, Malaysia's future success will depend on its ability to deepen local participation, strengthen domestic champions and foster stronger ecosystem collaboration. Through strategic facilitation, industry partnerships and ecosystem-building initiatives, MIDA remains committed to supporting this transformation and ensuring Malaysia remains a competitive and trusted semiconductor hub.

Ultimately, technology investments can only be sustained by a pipeline of highly skilled talent. As demand grows for expertise in areas such as chip design, advanced packaging, automation engineering, AI applications and semiconductor equipment development, closer collaboration between industry, academia and training institutions will be essential to ensure workforce readiness.

The message from SEMICON SEA 2026 was clear: Malaysia possesses the industrial depth, talent base and ecosystem strengths required to compete at the highest levels of the semiconductor industry. The task ahead is to accelerate capability development, deepen ecosystem integration and strengthen participation in higher-value segments. Those that can move fastest in building resilient, innovation-driven supply chains will be best positioned to shape the future of the global semiconductor industry—and Malaysia has the opportunity to be among them.

This article draws on insights from the Strategic Panel Session 'Advancing Malaysia's Semiconductor Ecosystem Through Strategic Supply Chain Integration & Capability Enhancement', held in conjunction with SEMICON SEA 2026, moderated by YBhg. Dato' Dr. Mohd Sofi Osman.

The Unsung Heroes: Why Malaysia's Chip Success is Written in ESI

Discussions surrounding Malaysia's rise as a global semiconductor powerhouse - which accounts for roughly 13% of global back-end chip testing and packaging, and over 7% of total global semiconductor trade - usually picture state-of-the-art factories, pristine cleanrooms, and the high-tech assembly lines of Penang, Kulim, or Johor. Yet behind every billion-ringgit semiconductor investment lies a foundational ecosystem that rarely makes the headlines.

To illustrate, the semiconductor value chain functions much like a large-scale theatrical production: The massive technology brands may get top billing, but their operations cannot succeed without the dedicated technical crew building the sets, maintaining the equipments, and keeping the running behind the scenes.

In the microchip world, this vital crew is represented by the **Engineering Supporting Industries (ESI).**

Amid today's increasingly complex global supply chains, driven by geopolitical and technological shifts, this "hidden backbone"—comprising precision machining, automation support, and specialised maintenance—is transitioning from behind the scenes into the spotlight. It is no longer merely a support system; it has become one of Malaysia's key competitive advantages.

The New Investment Paradigm: No Ecosystem, No Deal

Historically, developing nations attracted massive foreign investment (FI) primarily through conventional incentives: competitive real estate pricing, tax holidays, and low labour costs. The implicit promise to multinational anchor companies was: **"Build your factory here, and the local supply chain will eventually catch up."**

Today, that investment playbook is no longer sufficient.

In an era of exponential demand for AI chips and automotive electronics, tech giants face compressed product lifecycles and stringent operational timelines. brutal time-to-market pressures and unforgiving structural bottlenecks. Consequently, multinational corporations can no longer afford long lead times for local supplier development.

As a result, investment decisions increasingly prioritise turnkey **supply chain readiness.** Global anchors favour economies with mature, pre-certified, and operationally integrated ecosystems that facilitate immediate integration from day one. In the absence of a comprehensive network of precision engineers, calibration experts, and toolmakers, capital will inevitably migrate to more prepared and ready countries.

What exactly is ESI (And Why Does It Matter?)

Importantly, ESI is not a one-size-fits-all model; it is divided into **back-end support** (such as high-volume assembly, testing, packaging, jigs, and precision tooling) and **front-end support** (such as wafer fabrication equipment parts and high-tolerance machining). Each of these activities demands completely different technical specifications, strict quality standards, and distinct levels of supplier readiness.

Semiconductor fabrication is among the most complex, sophisticated, and capital-intensive processes globally. Under such unforgiving tolerances, a microscopic speck of dust or a machine part misaligned by a fraction of a millimetre can result in a catastrophic yield loss and severe financial deficits.

This highlights the critical role that ESI companies play as the technical foundation safeguarding operational uptime. Specifically, they provide:

- **Precision Machining:** Crafting high-tolerance components and machine parts that require micron-level accuracy.
- **Jigs & Fixtures:** Building the specialised tools and holders that ensure absolute repeatability across millions of cycles.
- **MRO (Maintenance, Repair, and Overhaul):** Ensuring the continuous optimisation of sophisticated, high-capital fabrication machinery.
- **Automation & Robotics:** Integrating the smart systems and automated robotics for delicate wafer handling.
- **Surface engineering and heat treatment:** Enhancing the structural integrity of high-performance industrial components.

The Bottom Line: Ultimately, ESI represents far more than capital expenses. It directly governs manufacturing throughput, yield optimisation, and overall cost efficiency.

Malaysia Already Has a Strong Engineering Base

Far from being a nascent sector, Malaysia's ESI ecosystem is exceptionally robust and far more mature than many realise.

MIDA's records indicate that Malaysia is home to hundreds of engineering supporting firms, each operating within highly specialised technical subsectors:

Subsector	Number of Projects
Casting	133
Cutting Tools	3
Forging	11
Heat Treatment	22
Jigs & Fixtures	39
Kitchen Ware	1
Machining	541
Moulds, Tools & Dies	561
Others	37
Stamping	201
Surface Engineering	186

These specialised operations underpin a broad range of industries, including semiconductors, aerospace, medical devices, automotive, and industrial automation. Many Malaysian companies today have successfully scaled into advanced capabilities such as:

- High-precision CNC machining
- Automation system integration
- Semiconductor equipment fabrication support
- Cleanroom-compatible manufacturing
- Advanced tooling and fabrication
- Precision metal stamping and engineered components

Long-standing industrial clusters in Penang, Kulim in Kedah, Selangor, and Johor have fostered highly integrated supplier networks capable of supporting complex manufacturing ecosystems.

This deep-rooted industrial maturity continues to be one of the key factors behind Malaysia's success in attracting high-profile semiconductor investments.

The "China+1" Shift: Why "Local" is the New Global

The global semiconductor landscape is undergoing a profound structural realignment. Spurred by supply chain lessons and an evolving trade landscape, global tech giants are aggressively diversifying their manufacturing bases through the **"China+1" strategy. In evaluating alternative locations,** global chipmakers increasingly choose Malaysia due to its distinct structural advantages. Decades of industrial clustering have given rise to a mature ecosystem boasting robust intellectual property (IP) protection, well-developed Free Industrial Zones (FIZs), a highly skilled, English-proficient engineering talent pool, and a seamless, facilitative regulatory framework. This positions the local ecosystem to seamlessly absorb high-value diversifications.

Expansion projects are taking place across Malaysia's industrial hubs. From an operational standpoint, a robust local ESI network provides MNCs with transformative advantages, enabling them to:

- **Reduce lead times** for critical spare parts from weeks to hours.
- **Mitigate global shipping bottlenecks** and sudden border delays.
- **Access immediate , on-site troubleshooting** for complex, high-capital machinery, such as an unexpected equipment or machinery failure.

By having and maintaining a reliable, highly responsive local engineering ecosystem, Malaysia transitions from being a temporary manufacturing pitstop into an indispensable, resilient global technology anchor.

The Reality Check: Where Local Firms Are Stalling

However, unlocking the full potential of these opportunities requires addressing several challenges. If supply chain readiness represents the primary benchmark for attracting investment, Malaysia's local small and medium enterprises (SMEs) must navigate specific structural headwinds to sustain the country's competitiveness.

The Challenge	What It Actually Means
The Value-Add Trap	Too many local firms remain stuck doing low-margin, basic fabrication rather than migrating into high-value, semiconductor-grade work.
The Technical Capability Gap	There is a critical shortage of advanced skillsets required for ultra-precision machining and advanced materials engineering.
The Scale and Capacity Constraints	The fragmented nature of many local companies that limit their ability to handle the massive volume and stringent delivery requirements of global Tier-1 MNCs.
High Capital Expenditure Requirement	Penetrating into the front-end supply chains requires a significant capital commitment alongside prolonged qualification timelines.
The Compliance and ESG Imperative	While meeting international quality certifications is mandatory, **ESG (Environmental, Social, and Governance)** compliance is now a critical, non-negotiable metric. Adopting a passive stance towards sustainability is no longer viable, as modern supply chains strictly mandate green manufacturing, carbon tracking, and ethical labour standards; local SMEs who fail to adapt risk disqualification by global MNCs.

Village

Elevating Malaysia's ESI ecosystem demands deliberate, highly coordinated actions from the government and regulatory bodies, multinational corporations, and local firms. While initiatives such as supply chain programmes and strategic match-making platforms are a start, the industry needs to intensify its focus on a few critical levers:

- **Deepening MNC–SME Collaboration:** Encouraging large multinationals to actively mentor local suppliers, thereby accelerating structured knowledge transfer and raising local technical standards to meet global expectations.
- **Industry 4.0 Incentives:** Expanding targeted financial support to help local businesses adopt automation, smart sensors, and digitised workflows (such as digital twin systems).
- **Workforce Upskilling:** Updating engineering and mechatronics curricula to create a future-ready workforce capable of managing highly digitalised production environments.
- **Strategic Industrial Clustering:** Strengthening regional tech hubs like the Kulim Hi-Tech Park and Penang for a seamless ecosystem collaboration.
- **Anchor Supply Chain Capability Enhancement:** Accelerating co-investment models and agile policy support to give global tech giants the confidence to anchor their long-term operations here.

National frameworks like the **New Industrial Master Plan (NIMP 2030)** and the **National Semiconductor Strategy (NSS)** serve as a strong foundation driving Malaysia's ESI evolution. Rather than just offering passive roadmaps, these initiatives actively support rapid industrial upgrading, deeper supply chain integration, advanced technology adoption (such as Industry 4.0), and enhanced global competitiveness across the entire semiconductor ecosystem.

The Final Verdict

Malaysia's engineering supporting industries are undergoing a profound structural evolution. They are evolving from basic back-office support into a core pillar of Malaysia's high value industrial future.

Ultimately, Malaysia's long-term competitiveness in the global semiconductor landscape won't be determined by high-profile,multi-billion-ringgit production facility announcements—it will depend increasingly on the maturity, absolute readiness, and agility of the local engineering ecosystem that is working behind the scenes.

And as the global semiconductor race intensifies, these once-unsung heroes will pave our way into the global value chain. **Ultimately, Malaysia's ESI should no longer be viewed merely as auxiliary suppliers, but as strategic enablers of technological sovereignty, supply chain resilience, and long-term industrial competitiveness.**

For more information, contact MIDA's Electrical & Electronics Division at https://www.mida.gov.my/staffdirectory/electrical-electronics-division/

Heng Hiap Industries Sdn. Bhd. (HHI): Building Global Circularity Through Integrated Recycling

Heng Hiap Industries Sdn. Bhd. (HHI) is a Malaysian-grown success story in the global circular economy, demonstrating how innovation, sustainability, and strategic expansion can transform environmental challenges into economic opportunities. As a **fully integrated plastic recycling and manufacturing** company, HHI has built a **robust end-to-end ecosystem that converts post-consumer plastic waste into high-quality recycled resins for international markets.**

From its headquarters and core operations in **Pasir Gudang, Johor,** HHI manages the entire **recycling value chain from collection, sorting, and washing to compounding and extrusion.** This integrated model enables the company to deliver consistent, traceable, and high-performance recycled materials tailored for industries such as **automotive, electrical and electronics (E&E), and industrial packaging.** Today, HHI **exports to customers in 41 countries,** serving leading multinational corporations and establishing itself as a trusted global supplier of sustainable materials.

Driving a High-Impact Circular Project in Malaysia

HHI's current project **focuses on expanding its advanced recycling capabilities and strengthening its position in circular material solutions.** The company's operations in Johor are centred on polypropylene (PP) and polyethylene (PE) recycling and compounding, with an increasing emphasis on advanced feedstock preparation for chemical recycling processes such as pyrolysis.

This project not only strengthens Malaysia's sustainable manufacturing capabilities but also contributes significantly to employment and income generation. HHI's ecosystem is supported by **a network of over 28,000 independent recycling operators,** creating economic opportunities, particularly for **local communities involved in waste collection and processing.** Within the company, HHI continues to create skilled employment opportunities in areas such as engineering, quality control, sustainability management, and advanced materials development.

In addition, HHI produces **certified Ocean Bound Plastic (OBP) materials** with full traceability and is

actively developing recycled resins suitable for food-grade applications through downstream decontamination processes. These efforts reflect the company's commitment to moving up the value chain while supporting global sustainability goals.

From Local Foundations to Global Expansion

HHI's decision to establish and expand its operations in Malaysia was driven by the country's strategic location, established industrial ecosystem, and access to regional and global markets. Malaysia also provides a strong foundation for manufacturing and export-oriented industries, enabling companies like HHI to scale efficiently.

HHI's global expansion was a natural progression, driven by increasing international demand for sustainable materials and tightening environmental regulations in key markets such as **Europe, the United States,** and the **Asia Pacific** region. HHI recognised early that global brands are seeking reliable partners capable of delivering not just recycled materials, but also transparency, traceability, and compliance with international standards.

By leveraging its integrated operations and strong upstream control, HHI has successfully differentiated itself in the global market. Its ability to customise materials, ensure consistent quality, and meet stringent certification requirements has been instrumental in securing long-term partnerships with multinational clients.

Building Credibility Through Certifications and Global Engagement

A key pillar of HHI's international success lies in its strong commitment to certification and compliance. The company has obtained several globally recognised certifications, including **the Global Recycled Standard (GRS), ISCC PLUS, Zero Plastic Ocean certification for Ocean Bound Plastic, and B Corporation certification.** These certifications demonstrate HHI's commitment to responsible, transparent, and traceable practices - qualities that are increasingly important in global supply chains.

HHI's certification-driven approach has enabled it to build trust with international customers while maintaining competitiveness in highly regulated markets. The company is also actively engaged in global industry platforms such as K Fair Düsseldorf and the Plastic Recycling World Conference, where it showcases its innovations and strengthens its international network. Through these efforts, HHI has not only expanded its global footprint but also contributed to shaping industry standards and advancing the adoption of circular economy practices worldwide.

Support from Government Agencies and DIAF-ESG

HHI's growth journey has been significantly supported by the Malaysian government, particularly MIDA and MATRADE. These agencies have played an important role in facilitating the company's internationalisation efforts through market access support, trade promotion initiatives, and strategic advisory services.

Importantly, HHI has also benefited from **MIDA's Domestic Investment Accelerator Fund – ESG Adoption (DIAF-ESG),** which supports companies in enhancing their environmental, social, and governance (ESG) practices. The grant has enabled HHI to further strengthen its sustainability framework, improve operational efficiencies, and align its processes with global ESG standards.

This support has not only enhanced HHI's competitiveness but also accelerated its ability to meet the evolving requirements of international markets. Participation in programmes such as the Mid-Tier Companies Development Programme has further provided strategic guidance and exposure, enabling HHI to scale its operations and expand globally with confidence.

Key Insights for Industry Players

HHI's journey offers several valuable lessons for companies seeking to grow sustainably and expand into international markets. A strong and reliable upstream ecosystem is essential for ensuring supply consistency and operational resilience. At the same time, prioritising certification and compliance is critical for building trust and facilitating access to international markets. Companies should focus on long-term value creation through product performance, reliability, and sustainability, rather than on cost competitiveness alone. Collaboration across the value chain remains a key driver of innovation, growth, and long-term resilience.

Shaping the Future of Sustainable Plastics

As the global transition toward a circular economy gains momentum, HHI continues to position itself at the forefront of sustainable materials innovation.

By combining operational integration, advanced recycling capabilities, and strong ecosystem partnerships, the company is delivering scalable and certified solutions that meet the needs of global industries.

HHI's journey demonstrates that with the right strategy, support, and commitment to sustainability, Malaysian companies can successfully compete on the global stage while contributing to environmental preservation and economic development.

Through its continued expansion and innovation, HHI is not only transforming plastic waste into valuable resources but also shaping a more resilient and sustainable future for the plastics industry worldwide.

Applications for the DIAF-ESG Grant remain open until 31 October 2026. For more information, please visit **https://www.mida.gov.my/forms-and-guidelines/**

NCER's Strategic Border Development Catalyses High-Value Investments, Taps ASEAN Market and Global Supply Chain Shifts

The Northern Corridor Economic Region (NCER) is reshaping the Malaysia–Thailand border into a strategic gateway for advanced manufacturing, cross-border logistics and technology-driven industries. Anchored by the New Investment Framework (NIF), which prioritises high-value investments and high-quality employment, the region is accelerating advanced manufacturing growth and positioning Northern Region as a prime destination amid the global China +1 supply chain realignment.

Leveraging the dual logistics nodes of Perlis Inland Port (PIP) near Padang Besar and the Bukit Kayu Hitam Inland Clearance Depot (BKH ICD) at the busiest border crossing, NCER is integrating thematic industrial parks – **Chuping Valley Industrial Area (CVIA), Kedah Rubber City (KRC) and Kedah Science & Technology Park (KSTP)** – under a unified border economic development framework. This alignment ensures complementary planning, seamless cross-border connectivity, and direct access to the ASEAN market of over 680 million people, with onward reach into the Greater Mekong Subregion.

The integrated border strategy is deliberately designed to capture ongoing shifts in global manufacturing. The China +1 strategy is more than a short-term trend. It reflects a structural realignment of supply chains. By combining industrial readiness, logistics connectivity, innovation ecosystems, ESG-aligned renewable energy, and trade facilitation at its border gateways, NCER offers a uniquely de-risked, cost-competitive launchpad into the ASEAN market. The NIF further strengthens this proposition by targeting high-value, high-technology investments that generate quality employment for Malaysians, with a focus on strengthening Malaysia's manufacturing base and industrial competitiveness. Early outcomes from CVIA, PIP and KRC demonstrate the effectiveness of this approach, delivering tangible results and catalysing follow-on investor confidence.

CVIA and PIP – Dual Logistics-Industrial Powerhouse

CVIA secured a landmark investment from global manufacturer Jabil last year. Initial operations began in late-December 2025, with phased expansion under way and a healthy pipeline of follow-on investments. NCER is in the final stages of concluding several more major commitments in CVIA before year-end.

In tandem, the PIP was fully completed this year, with NCER delivering external infrastructure including the border road, flyover and railway spur line, while internal infrastructure was developed by Mutiara Perlis Sdn. Bhd. PIP commenced initial operations in late-2025 and is progressively scaling throughput capacity throughout 2026, transforming Padang Besar into an important multimodal logistics hub that shortens time-to-market for goods moving across the ASEAN land bridge.

KRC – Smart Manufacturing for Global Markets

At KRC, Prinx Chengsan committed a cumulative RM2.6 billion investment over 15 years to develop a smart, eco-friendly tyre manufacturing facility. With initial operations expected in Q4 2026, the project will generate significant socio-economic benefits, particularly in skilled job creation and vendor development. NCIA is now finalising several additional major investments to accelerate the fulfilment of KRC Phase 1 by year-end.

KSTP – High-Tech Ecosystem at Bukit Kayu Hitam

KSTP Phase 2A infrastructure has been under construction since 2024 and is on track for completion by December 2026. Strategically located next to the brownfield industrial area and the BKH ICD, KSTP is set to receive investments as early as next year. Once fully operational, it is projected to attract RM12.9 billion in investments and create 23,244 high-value job opportunities. NCER has curated a targeted investment strategy focusing on nanotechnology, high technology and aerospace, complementing existing industries and transforming Bukit Kayu Hitam into an advanced manufacturing and innovation corridor.

Leveraging Regional Platforms and Strategic Frameworks

Thematic industrial parks require proactive long-term planning to remain relevant amid evolving economic conditions. NCER is leveraging the Indonesia–Malaysia–Thailand Growth Triangle (IMT-GT) platform to deepen regional integration in its border development planning, while the NIF ensures that each ringgit of incentivised investment delivers high-value jobs and technology transfer.

Early results from CVIA, PIP and KRC this year serve as strong proof points, accelerating investor engagement compared to previous cycles. The investment pipeline remain robust, with NCER's positioning—anchored on border connectivity, ASEAN market access, and supply chain diversification, continuing to gain traction among global investors.

NCER acknowledges the continued support of the Ministry of Economy, Ministry of Investment, Trade and Industry (MITI), MIDA, State Governments, local authorities and all agencies involved in facilitating investments across the Northern Region.

The Road Ahead

NCER's strategic border development reinforces Malaysia's position within regional and global supply chains by transforming the Malaysia–Thailand border into a high-value investment gateway. Through integrated infrastructure, thematic industrial parks, and targeted investment facilitation, the Northern Region is strengthening its position as a competitive destination for advanced manufacturing and logistics investment.

For more information about NCER, please visit **the NCER homepage at www.ncer.com.my**

Disclaimer: All figures in this article are under the purview of NCER and are for informational purposes only. For specific details regarding investments and initiatives, please refer to official NCER communications.

Malaysia Strengthens Semiconductor Investment Positioning Through Strategic Engagements in China

MIDA Shanghai & Invest Melaka

As global semiconductor supply chains continue to evolve, Malaysia is strengthening its position as a strategic hub for advanced manufacturing, semiconductor expansion, and high-value technology investments. Through continuous engagements with global industry players and participation in key international platforms, the country continues to attract quality investments, deepen technological collaboration, and reinforce its role within the regional semiconductor ecosystem.

One of the key platforms supporting these efforts was **SEMICON China 2026,** held at the Shanghai New International Expo Centre (SNIEC), which brought together global semiconductor companies, investors, technology leaders, and policymakers from across the industry value chain. Recognised as one of the semiconductor industry's leading international exhibitions, the event served as an important avenue for investment promotion, technology exchange, and supply chain collaboration.

Malaysia's participation, jointly driven by MIDA Shanghai and Invest Melaka, reflected the country's broader commitment to strengthening international industry linkages while showcasing Malaysia's readiness to support next-generation semiconductor and advanced manufacturing activities.

Strengthening Malaysia's Semiconductor Value Proposition

Throughout the engagements, Malaysia's growing role within the global semiconductor ecosystem was prominently highlighted. The country continues to build on its established strengths in semiconductor assembly, testing, and packaging, while accelerating, continuing to expand further into higher-value segments such as integrated circuit (IC) design, advanced packaging, and front-end semiconductor activities under the National Semiconductor Strategy (NSS).

Representing MIDA Shanghai, Mr. Muhammad Sawaddee, Consul (Investment) and Director of MIDA Shanghai, highlighted Malaysia's strong investment momentum, supported by a balanced contribution between domestic and foreign investments, alongside the country's well-developed industrial ecosystem and investor-friendly policies. He also highlighted Malaysia's strengths as a global semiconductor hub, noting that the country accounts for approximately 7% of global semiconductor trade and commands an estimated 13% global market share in the back-end assembly, testing, and packaging segments

Malaysia's semiconductor ecosystem today is supported by:

- Strong industrial clusters across Penang, Selangor, Johor, and Kuala Lumpur
- Established multinational supply chains
- Skilled engineering and technical talent
- Advanced infrastructure and logistics connectivity
- National frameworks supporting high-technology industries and innovation-driven growth

Showcasing Melaka's Emerging High-Tech Industrial Ecosystem

As part of the broader investment promotion efforts, Invest Melaka highlighted the state's transformation into an emerging destination for high-technology industries, particularly in Electrical & Electronics (E&E), semiconductors, aerospace, and Industry 4.0-driven manufacturing.

Led by YB Datuk Khaidirah Datuk Seri Abu Zahar, Deputy EXCO of Investment, Industry and TVET Development (Melaka), the engagements showcased Melaka's strategic development initiatives, including the expansion of industrial parks designed to accommodate high-growth and technology-driven industries.

Among the developments highlighted were:

- German Technology Park – GTP (418.63 acres)
  Electrical & Electronics, Machinery & Equipment, Medical Devices, Automotive, Green Technology, Digitalisation, Aerospace, R&D
- ELKAY Industrial Park - Phase 2 (601.75 acres)
  Artificial Intelligence (AI), Robotics, Internet-of-Things (IoTs), Electric Vehicles (EVs) Component Manufacturing, Recycle EV Components, Supply & Shipping, Pharmaceutical, Renewable Energy
- MCorp Hitech Park – MHTP (6,142.92 acres)
  Semiconductor, Electrical & Electronics, Process Control & Automation Equipment, Logistics & Warehouse, Pharmaceutical & Medical Devices, Services & Supporting Industries

Melaka's strategic location along the west coast of Peninsular Malaysia—situated between the Johor-Singapore Special Economic Zone (JS-SEZ) and major industrial corridors in Selangor, Penang, and Kedah—further strengthens its attractiveness as an integrated manufacturing and logistics hub.

Advancing Talent Development and Ease of Doing Business

Talent development and investor facilitation also formed a key part of the investment narrative presented by Invest Melaka during the engagements.

Backed by the Melaka State TVET Council, the state continues to strengthen its talent pipeline through a network of public and private higher learning institutions, alongside Technical and Vocational Education and Training (TVET) centres aligned with industry requirements.

In parallel, the Melaka Industrial Booster (MIB) initiative was highlighted as part of the state's efforts to further improve ease of doing business and accelerate industrial project implementation. The initiative, which brings together 29 agencies under a One Stop Centre framework, supports investors through streamlined coordination, facilitation, and approval processes.

Malaysian Companies Showcase Cutting-Edge Technology

Complementing these investment efforts, Malaysia's presence was further strengthened by several homegrown technology firms exhibiting at the event, demonstrating the depth of the nation's semiconductor ecosystem. Their participation served as a testament to the successful promotional efforts of MIDA in nurturing local champions capable of competing on the global stage.

ViTrox Corporation Berhad unveiled a suite of AI-powered inspection systems, including:

- **TH3000i Smart Tray Based Vision Handler (AI):** Featuring Short-Wave Infrared (SWIR) technology for advanced packaging inspection.
- **PX730Ai Die Sorting, Inspection & Package Solution:** Combining high-precision die sorting with six-sided automated optical inspection.
- **WiX Ai Smart Wafer Inspection Machine:** Enabling sub-micron defect detection for smart factory readiness.
- **V510Ai Vision Pro Smart 3D AOI and VR20Ai G2 Post Seal Vision Handler.**

Other Malaysian companies participating included **Pentamaster Instrumentation, QES Mechatronic, TT Vision Technologies, NSW Automation, and Advanced Material Engineering,** among others. Their participation at SEMICON 2026 Shanghai not only showcased Malaysian technological capabilities but also served as a strong testament to the country's conducive business environment.

Building Long-Term Investment Partnerships

Beyond exhibition participation, MIDA Shanghai and Invest Melaka also facilitated strategic business meetings and industry discussions involving existing investors, Malaysian companies, and potential partners from China.

A Business Roundtable led by YB Datuk Khaidirah Datuk Seri Abu Zahar was also convened under the theme **"Futuring Manufacturing: Digitalisation, Automation & Precision Engineering,"** bringing together representatives from approximately 10 strategic entities, alongside industry leaders, investors, and key stakeholders. The session provided a platform to exchange insights on the evolving manufacturing landscape, particularly in advancing smart manufacturing, automation, and precision engineering capabilities.

Discussions focused on emerging trends, challenges, and opportunities in building resilient, future-ready industrial ecosystems, while reinforcing confidence in Melaka's value proposition as a preferred investment destination. The dialogue also highlighted Melaka's aspirations to support business growth through the development of an integrated automotive power semiconductor ecosystem.

The discussions further reinforced Malaysia's commitment to developing resilient industrial ecosystems supported by:

- Strong talent development initiatives
- Competitive industrial infrastructure
- Local SME participation and supply chain integration
- Facilitative investment policies and governance

Sustaining Malaysia's Semiconductor Momentum

As global industries continue to diversify supply chains and accelerate technology investments, Malaysia remains well-positioned to strengthen its role within the regional and global semiconductor ecosystem.

This commitment is reflected through active participation in major industry platforms, including SEMICON China 2026 in March and the hosting of SEMICON Southeast Asia 2026 in Kuala Lumpur this May, providing valuable opportunities to showcase Malaysia's expanding capabilities across the semiconductor and advanced manufacturing value chain.

Through continuous engagement with international industry players and strategic collaboration platforms, MIDA Shanghai and Invest Melaka will continue promoting the nation's strengths in semiconductors, advanced manufacturing, and high-technology industries as well as supporting the country's aspiration to become a leading innovation-driven investment destination in Asia.

Companies interested in exploring investment opportunities in Malaysia's semiconductor and high-technology sectors may connect with **MIDA Shanghai at shanghai@mida.gov.my.**

Advanced Packaging: How Malaysia is Packaging the Future of AI

When we think of "packaging," we usually picture a cardboard box wrapped in colourful paper, tied with a ribbon and a card. It is the final layer that protects a gift until it is opened.

In semiconductors, packaging is far more than a box - and the "gift" inside never gets unwrapped.

Imagine a microscopic city of billions of transistors - incredibly expensive, extraordinarily delicate, and so sensitive that a single speck of dust could destroy it.

For more than 50 years, Malaysia has been a global leader in encapsulating and connecting these chips through semiconductor packaging and testing.

We ship 13% of the world's packaged chips this way.

The game today has fundamentally changed.

The New Starting Point: From Chips to Chiplets

In the past, the process was simple: each package contained only one chip.

With the demands of AI, smartphones, AR/VR headsets, and other advanced applications, a single chip is no longer sufficient. It is no longer enough to meet the performance demands of today's technologies.

The industry has moved toward "Chiplets."

Chiplets can be arranged side by side, stacked on top of one another, and reconfigured like high-tech "LEGO" blocks to create a single powerful superchip.

This means the process now begins with Integrated Circuit (IC) Design, but with a new twist. IC designers must now understand how these blocks will be stacked, interconnected, and arranged before they are even built.

If these chip architects do not understand how these "LEGOs" will be bonded together or tested later, the final product will simply not function.

A More Advanced Supply Chain

Transforming a design into a finished product is now a sophisticated "LEGO" assembly process involving highly specialised equipment worth millions of dollars and precision beyond the capability of the human eye.

Imagine placing more than 10 microscopic connections solder across the width of a single human hair. That is the precision required to bond chiplets together. And then test to make sure the assembly works.

This needs a very complicated and interconnected chain of machines costing millions, with expertise and excellence in how to use them:

- **IC Design:** The blueprint phase where chiplets are designed to "talk" to each other at lightning speed.
- **Wafer Fabrication:** Complex circuits are etched onto a silicon wafer.

- **The Wafer & Dies:** A single wafer contains hundreds of individual chips, which become known as dies once separated.
- **Assembly & Advanced Packaging (AAP):** Where the magic happens. Individual dies from different wafers are stacked with microscopic accuracy - measured in microns - and bonded into a single, high-performance unit, most likely with thousands of microscopic leads.
- **Test:** Using Automated Test Equipment (ATE), engineers ensure that every one of the millions of microscopic connections performs as intended, and the whole assembly works as designed!

Redefining What is "Made-In-Malaysia"

This process is now so complex and moves so fast that no single company can master it alone. Traditionally, local companies relied on multinational corporations (MNCs) to provide the designs and technical specifications. For traditional chips, we still do.

Malaysia became recognised globally for excellence in manufacturing execution. Made in Malaysia.

But to lead in the age of AI, we must move from following customer instructions to understanding "external trends" (anticipating global needs).

And charting our own course alongside our customers.

It is not an easy task and it is something Malaysia has not attempted before.

This is why we need a "Collaborative Mission" - a coordinated effort involving partners across every stage of the supply chain.

In support of this vision, **Malaysia's Advanced Packaging Consortium (MAPC)** was formed by five local champions:

- **SkyeChip:** The architects providing the latest IC Design and chiplet expertise.
- **Inari Amertron:** The global powerhouse providing the OSAT (Outsourced Semicon Assembly and Test) production lines.
- **Pentamaster:** The industry experts in ATE and instrumentation.
- **NSW Automation:** Leaders in high-precision assembly equipment and fluid dispensing for micro-bumps.
- **FusionAP:** The specialist start up developing the leading-edge techniques on the Advanced Packaging process.

Together, these five companies form an industry consortium united by a common mission.

A New Mission: Enabling "Made-By-Malaysia"

The mission of the MAPC is to build a complete, home-grown Advanced Packaging ecosystem from scratch. This shift - from "following instructions" to "defining the roadmap" - is a pivotal moment for our nation.

It is the intention of our National Semiconductor Strategy (NSS), announced in May 2024.

We are no longer just putting expensive chips in packages; we are attempting to design our future.

Standing still is not an option.

By working together, they have a greater opportunity to shape Malaysia's future, contributing to tech development by solving problems before the global players even ask. To do that, they have to work with others, locally, regionally and globally.

That is why three government ministries – Ministry of Science, Technology and Innovation (MOSTI), Ministry of Investment, Trade and Industry (MITI) and Ministry of Economy (KE), recently visited Penang to better understand the progress being made to bring MAPC to life. They saw a future where Malaysia is not just a "high-tech" manufacturing hub, but an emerging global innovation hub.

They heard about the mission goal: "To enable the nation to capture 7% of worldwide advanced packaging shipments by 2035." Today, Malaysia is just beginning that journey.

In the world of AI, standing still is not an option. Neighbouring countries are moving quickly and building their own capabilities. They will not need 50 years to reach where Malaysia stands today.

Malaysia Boleh!

MIDA and HLB Islamic IMFC Strengthen Strategic Collaboration to Empower SMEs in the Northern Region

As Malaysia continues to strengthen its domestic investment ecosystem, empowering local enterprises to grow, compete and integrate into global supply chains remains a key priority. In support of this agenda, MIDA and HLB Islamic organised an Entrepreneur Forum themed ***"Pengukuhan Usahawan Bumiputera Di Wilayah Utara: Perspektif Dasar Dan Trend Pasaran Semasa"*** in Sungai Petani, Kedah.

The forum brought together approximately 250 SME entrepreneurs from Kedah, Penang, Perak and Perlis, providing SMEs a platform to connect with financing opportunities, market access strategies and government support programmes.

Participants gained insights on sustainable financing, export readiness, e-invoicing implementation and financing facilitation from agencies including MATRADE, Bank Negara Malaysia (BNM), Syarikat Jaminan Pembiayaan Perniagaan (SJPP) and Lembaga Hasil Dalam Negeri Malaysia (LHDNM). MIDA also shared updates on the New Incentive Framework (NIF) and the Malaysia-Singapore Third Country Business Development Fund (MSBDF), while HLB Islamic highlighted initiatives such as BizDagang and Greening Halal Business.

A key highlight was the panel discussion, *"Memacu Juara Bumiputera: Akses dan Peluang Pembiayaan, Akses Pasaran, dan Rantaian Bekalan Global"*, featuring representatives from HLB Islamic, TERAJU, MARA, SME Corp. Malaysia and VentureTECH. The programme reflects the shared commitment of MIDA, HLB Islamic and the Kedah State Government to strengthen the competitiveness of local enterprises and support their participation in regional and global value chains.

Reinforcing Malaysia–Japan Economic Partnership Amid Global Uncertainty

Malaysia and Japan reaffirmed their commitment to deepening economic cooperation and strengthening supply chain resilience during a fireside chat between Tengku Datuk Seri Utama Zafrul Aziz, Chairman of MIDA and Senior Political Advisor to the Prime Minister, and H.E. Noriyuki Shikata, Ambassador of Japan to Malaysia.

Held at MIDA headquarters, the session brought together approximately 100 representatives from Malaysian government agencies, Japanese business organisations and leading financial institutions. Discussions focused on navigating global economic uncertainties while identifying new opportunities for bilateral collaboration.

Key areas of focus included energy security, supply chain resilience, investment opportunities in high-growth sectors, and Malaysia's New Incentive Framework (NIF), which emphasises investment quality, innovation, sustainability and economic complexity. Participants also exchanged views on strengthening industry engagement and supporting businesses seeking to expand their presence in Malaysia.

The dialogue highlighted growing opportunities for collaboration in strategic sectors such as semiconductors, digital transformation, advanced manufacturing, the green economy, aerospace and the halal industry. Both sides also underscored the importance of aligning Malaysia's National Energy Transition Roadmap (NETR) with Japan's Asia Zero Emission Community (AZEC) initiative to advance sustainable industrial development.

The engagement reflects the enduring strength of the Malaysia–Japan partnership and reinforces MIDA's commitment to facilitating high-quality investments that enhance economic resilience, technological advancement and long-term sustainable growth.

MIDA and MARA Partner to Strengthen Talent Development and Local Supply Chain Integration

Addressing talent shortages and strengthening local supplier participation remain critical to sustaining Malaysia's industrial growth. To support these priorities, MIDA and MARA have formalised a strategic partnership aimed at developing industry-ready talent and creating new opportunities for local enterprises to integrate into global supply chains.

A key initiative under the collaboration is the **PRIME Talent Hub,** a demand-driven platform where participating companies identify the technical skills and competencies required by industry. Eight companies have already committed to the initiative, namely **Medtronic Malaysia Operations Sdn. Bhd., EVE Energy Malaysia Sdn. Bhd., DayOne Data Centre, UWC Industrial Sdn. Bhd., Linergy Power Sdn. Bhd., Panasonic Industrial Devices Malaysia Sdn. Bhd., ND Paper (Malaysia) Sdn. Bhd., and Base Maintenance Malaysia Sdn. Bhd.**

The partnership will also provide MARA-linked enterprises, including Bumiputera businesses, with structured pathways to **participate in multinational supply chains** through MIDA's vendor development and supply chain programmes. Companies will also gain access to MIDA's Investment Coordination Platform (ICP) and Enterprise Growth Platform (EGP), supporting capability development, financing access and business expansion.

Aligned with the MADANI Economy Framework and the New Industrial Master Plan (NIMP) 2030, the collaboration reinforces efforts to strengthen Malaysia's industrial ecosystem by connecting talent development, enterprise growth and high-value investment opportunities.

DCN 2026 | DATA CENTRE NEXUS

DATA CENTRE NEXUS 2026

Malaysia's Premier Event for AI-Driven Digital Infrastructure and Sustainable Ecosystems

14 September 2026 | **Hilton Kuala Lumpur** | **400+ Participants** | **Government • Industry Investors • Ecosystem Partners**

WHAT IS DCN 2026?

DCN 2026 is MIDA's flagship event where global digital infrastructure leaders, hyperscalers, data centre operators, technology innovators, and local supply chain partners connect, collaborate, and shape a sustainable digital future.

Through strategic business matching and industry collaboration, DCN 2026 unlocks new partnerships, bridges global demand with local capabilities, and positions Malaysia's local supply chain to become a trusted partner in the AI-driven cloud and data centre ecosystem to strengthen Malaysia's position as a leading regional digital hub.

STRATEGIC NARRATIVE PILLARS

- AI-Driven Digital Infrastructure
- Sustainable & Resource-Efficient Infrastructure
- Local Ecosystem & Industrial Spillovers
- Digital Technology Accessibility & Adoption

WHAT TO EXPECT AT DCN 2026

- Keynote Sessions
- Panel Discussions
- Fireside Chats
- Executive Spotlight Series
- Business Matching Sessions
- Investment Engagement Sessions
- Networking Opportunities
- Technology Showcase

WHO SHOULD ATTEND?

INDUSTRY PLAYERS

- Hyperscalers & Cloud Providers
- Data Centre Developers & Operators
- Telecommunications & Connectivity Companies
- Submarine Cable & Network Operators
- Renewable Energy & Cooling Solution Providers
- Engineering, EPC & Technology Companies

ECOSYSTEM PARTNERS

- Financial Institutions & Investors
- Government Agencies & GLCs
- Universities, Research Institutions & Start-ups
- Local SMEs & Supply Chain Players
- Industry Associations & Professional Bodies

REGISTRATION OPENING SOON

Follow MIDA's official channels for the latest updates

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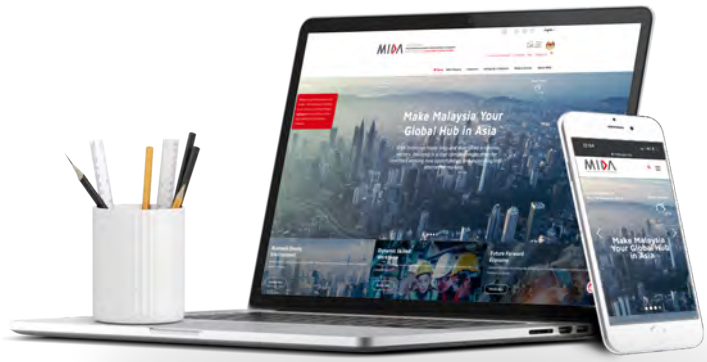

MIDA WEBSITE

With more than 70,000 average visits per month, our website provides useful and relevant information, serving as a reference for potential investors in doing business in Malaysia.

E-NEWSLETTER

With more than 40,000 registered subscribers and growing, our monthly English e-Newsletter contains the latest industry and services updates, as well as activities held throughout the month.

DIGITAL SIGNAGES

Our digital signages are situated within our HQ building. Located in the heart of Kuala Lumpur, MIDA's headquarters sees hundreds of visitors through its lobby every day.

Location
1. MIDA Lobby, Ground Floor
2. Business Information Centre (BIC), Level 2
3. Perdana Hall, Level 10
4. Corporate Reception Floor, Level 18

Refer next page for the price

Advertisement
Package

BRONZE PACKAGE

E-NEWSLETTER

- Full page: RM10,000 per issue
- Half page: RM6,000 per issue
- Quarter page: RM3,500 per issue

MIDA WEBSITE

- Homepage: RM1,500 per week

DIGITAL SIGNAGES

- Video wall, digital standee & LCD TV: RM3,000 per month

ADD-ONS

- Editorial only: from RM500
- Artwork resizing: from RM500

SILVER PACKAGE

Branded Content to be published in Invest Malaysia e-Newsletter, and amplified on MIDA digital platforms:

- 1 Full page full colour (advertorial) x 1 insertion (estimated between 250-300 words)
- Ads web banner on MIDA website home page (4 weeks)
- Advertisement on MIDA digital signages (4 weeks)

Visibility:

- An exclusive landing page in MIDA Website for the advertorial
- Social media amplifications on MIDA Facebook, X, LinkedIn, Instagram (2 x Postings)

RM18,000
Duration: 4 weeks

GOLD PACKAGE

Branded Content to be published in Invest Malaysia e-Newsletter, and MIDA digital platforms:

- 2 Full page full colour (advertorial) x 1 insertion (estimated between 500-600 words);
- Ads web banner on MIDA website home page (4 weeks)
- Advertisement on MIDA digital signages (4 weeks)

Visibility:

- An exclusive landing page in MIDA Website for the advertorial
- Social media amplifications on MIDA Facebook, X, LinkedIn, Instagram (4 x Postings)

RM24,000
Duration: 4 weeks

PLATINUM PACKAGE

Branded Content to be published in Invest Malaysia e-Newsletter, and MIDA digital platforms:

- 2 Full page full colour (advertorial) x 2 insertion (estimated between 500-600 words);
- Ads web banner on MIDA website home page (8 weeks)
- Advertisement on MIDA digital signages (8 weeks)

Traffic drivers to the articles:

- An exclusive landing page in MIDA Website for the advertorial
- Social media amplifications on MIDA Facebook, X, LinkedIn, Instagram (8 x Postings)

RM42,000
Duration: 8 weeks

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F&B PACKAGES		GOVERNMENT	PRIVATE
A	Inclusive of: •Refreshment •Tea Break •Lunch •Hi-Tea	From RM130 / Pax	
B	Inclusive of: •Refreshment •Tea Break •Lunch	From RM110 / Pax	
C	Inclusive of: •Refreshment •Tea Break/Hi-Tea	From RM70 / Pax	

PRIVATE MEETING ROOM

ROOM TYPES		GOVERNMENT	PRIVATE
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A	Inclusive of: •Refreshment •Tea Break •Lunch •Hi-Tea	From RM130 / Pax	
B	Inclusive of: •Refreshment •Tea Break •Lunch	From RM110 / Pax	
C	Inclusive of: •Refreshment •Tea Break/Hi-Tea	From RM70 / Pax	

TRAINING ROOM

ROOM TYPES		GOVERNMENT	PRIVATE
SIGMA\ GAMMA ROOM (40PAX)	Inclusive of: •Basic AV System •1 Flipchart •2 Mahjong Paper •2 Marker Pens	RM1,150	RM1,250

F&B PACKAGES	GOVERNMENT	PRIVATE
Inclusive of: •Refreshment •Lunch •Tea Break	RM80 / Pax	

*All rates are exclusive of :
- GST (0%)
  Service Staff, linen, dome, logistic (RM300)

*F&B by MIDA's panel caterers

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About MIDA

MIDA is the Government's principal investment promotion and development agency under the Ministry of Investment, Trade and Industry (MITI) to oversee and drive investments into the manufacturing and services sectors in Malaysia. Starting operations in 1967 with a relatively small set up of 37 staff, MIDA has grown to become a strong and dynamic organisation of over 700 employees. Headquartered in Kuala Lumpur Sentral, MIDA today has 12 regional and 21 overseas offices. MIDA continues to be the strategic partner to businesses in seizing the opportunities arising from the technology revolution of this era. For more information, please visit www.mida.gov.my and follow us on X, Instagram and Facebook, LinkedIn, TikTok and YouTube channel.

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